

BEELED

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MODEL: 5050SUGC

Features

- InGaN Green*3 Dice LED
- Size : 5.0mmx5.0mmx1.5mm
- High luminous intensity, high reliability and long life
- With ROHS Compliant



Descriptions

- The 5050 SMD LED is much smaller than lead frame type components thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained
- Besides, lightweight makes them ideal for miniature applications.etc

Usage Notes:

- Surge will damage the LED
- When using LED, it must use a protective resistor in series with DC current about 20mA

Applications

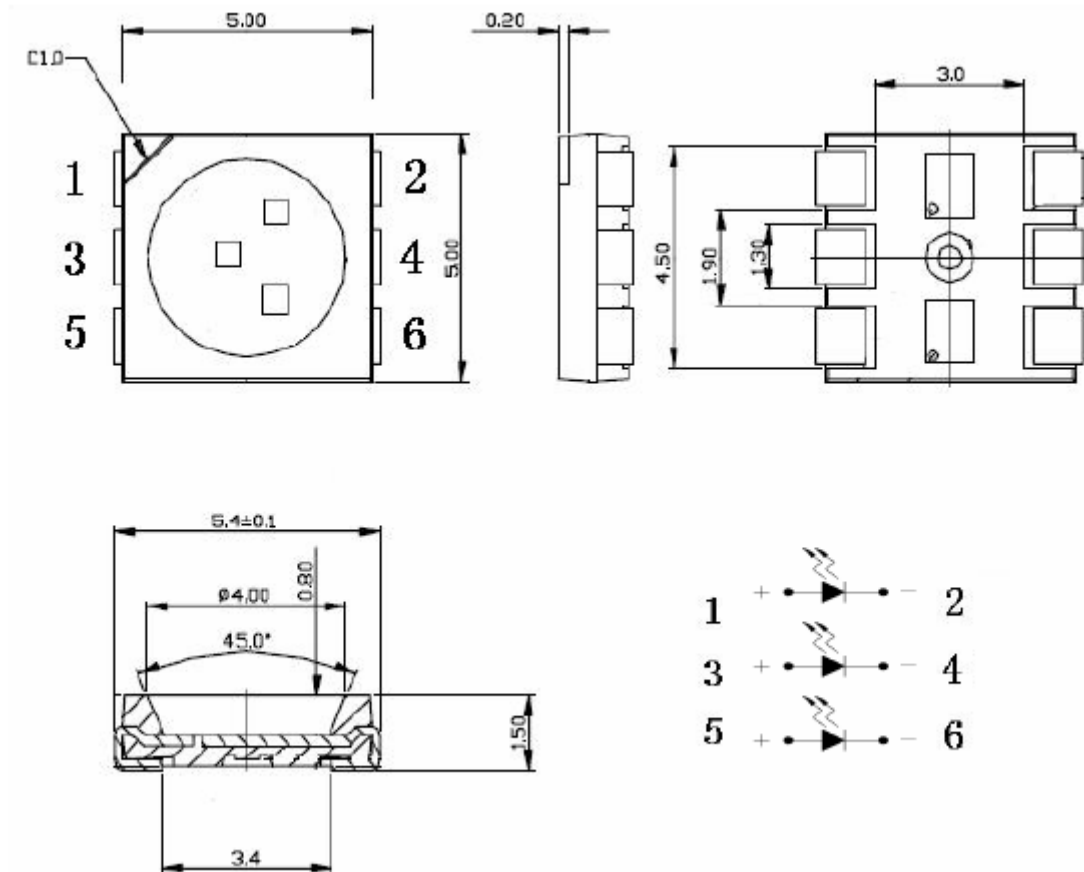
- Amusement equipment ∙
- Information boards ∙
- Flashlight for digital camera of cellular phone ∙
- Lighting for small size device.

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Device Selection Guide

LED Part No.	Chip		Lens Color
	Material	Emitted Color	
5050SUGC	InGaN	Ultra bright Green	Water clear

Package Dimensions



Notes:

- Other dimensions are in millimeters, tolerance is 0.25mm except being specified.
- Protruded resin under flange is 1.5mm Max LED.
- Bare copper alloy is exposed at tie-bar portion after cutting.

Absolute Maximum Rating ($T_a=25^{\circ}\text{C}$)

Parameter	Symbol	Absolute Maximum Rating	Unit
Peak Forward Current (Duty 1/10 @1KHz)	I_F	100	mA
Forward Current	I_{FM}	50	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	300	mW
Operating Temperature	T_{opr}	-40~+80	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-40~+100	$^{\circ}\text{C}$
Soldering Temperature	T_{sol}	Reflow Soldering : 260 $^{\circ}\text{C}$ for 10 sec. Hand Soldering : 350 $^{\circ}\text{C}$ for 3 sec.	

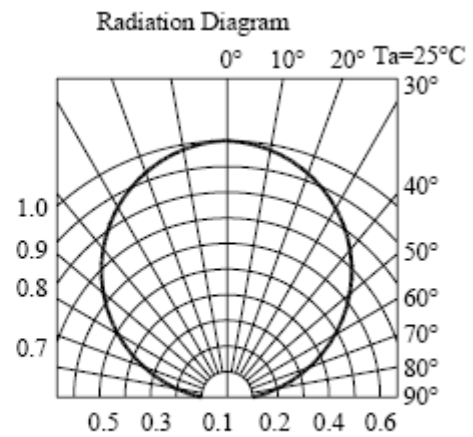
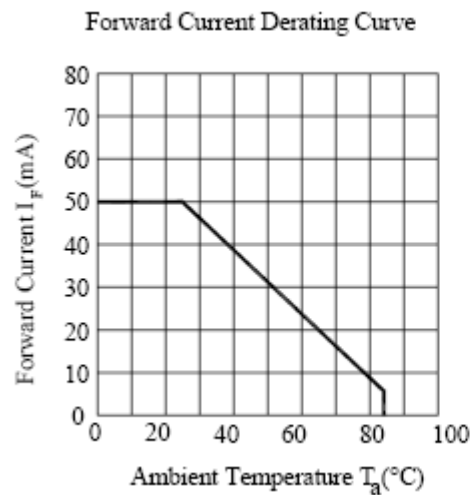
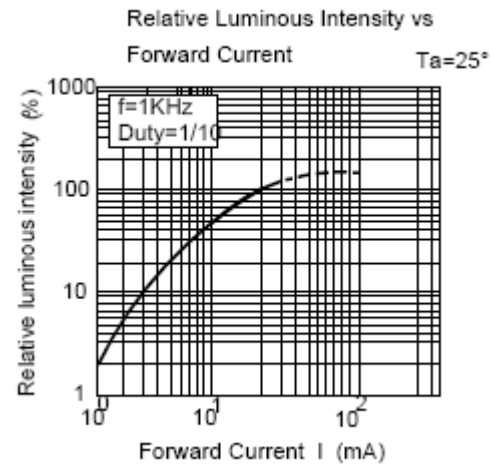
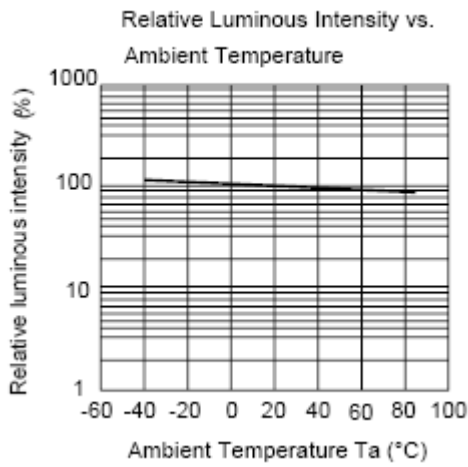
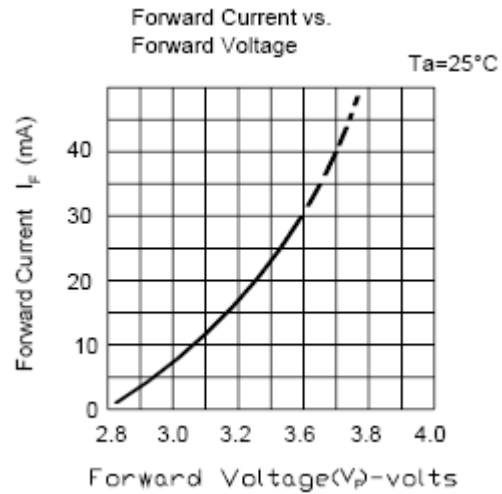
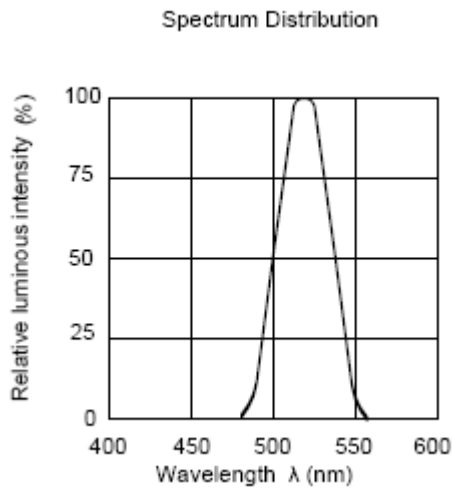
Electro-Optical Characteristics ($T_a=25^{\circ}\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I_v	5000	---	7000	mcd	$I_F=20\text{mA}$ (Note1)
Viewing Angle	$2\theta_{1/2}$	---	120	---	Deg	(Note 2)
Peak Emission Wavelength	λ_p	520	525	---	nm	$I_F=20\text{mA}$
Spectral Line Half-Width	$\Delta\lambda$	---	30	40	nm	$I_F=20\text{mA}$
Forward Voltage	V_F	3.0	---	3.4	V	$I_F=20\text{mA}$
Reverse Current	I_R	---	---	50	μA	$V_R=5\text{V}$

Note:

1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

Typical Electro-Optical Characteristics Curves



Reliability Test Items And Conditions

No	Item	Test Condition	Sample Number	Criteria for Judging	Ac/Re
1	Solder ability	T=235±5℃ T=5sec.	15	Good wetting	0/1
2	Soldering heat	T=260±5℃ T=10sec.	15	IV≥LSL* VF≤USL* IR≤USL	0/1
3	Rapid change of temperature followed by: damp heat, cyclic	L:-40℃ 10min (2~3) min H:+100℃ 10min 5cycle T= (25~55) ℃ RH: (90~95) % 2cycle 48h recovery time 2h	11	IV≥LSL VF≤USL IR≤USL	0/1
4	Damp heat, cyclic	T=(25~55)℃ RH= (90~95) % 6 cycle 144h recovery time 2h	11	IV≥0.7LSL VF≤1.1USL IR≤2USL	0/1
5	Electrical endurance	I _F =30mA T=1000h	22	IV≥0.7LSL VF≤1.1USL IR≤2USL	0/1
6	Storage at high temperature	T _{stg} =100±2℃ t=1000h	15	IV≥LSL VF≤USL IR≤USL	0/1
7	Terminal strength	Tensile: W=5N t= 30s Bending: W=2.5N 2times	15	No damage	0/1

*U.S.L.: Upper Standard Level

* L.S.L.: Lower Standard Level

APPLICATION NOTES:

1) Soldering:

① Manual soldering by soldering iron:

The use of a soldering iron of less than 25W is recommended and the temperature of the iron must be kept at no higher than 300°C.

② Reflow soldering:

a. The temperature profile as shown in Fig. 3 is recommended for soldering SMD LED by the reflow furnace.

b. Care must be taken that the products be handled after their temperature has dropped down to the normal room temperature after soldering.

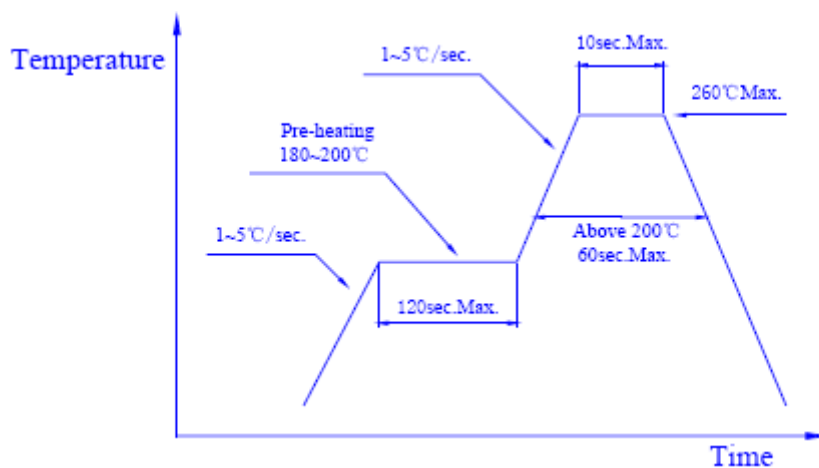


Fig.3

2) Post solder cleaning:

When cleaning after soldering is needed, the following conditions must be adhered to.

① Cleaning solvents: Freon TF or equivalent or alcohol.

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② Temperature: 50°C Max. for 30 seconds or 30°C Max. for 3 minutes

③ Ultrasonic: 300W Max.

3) OTHERS:

a. Care must be taken not to cause stress to the epoxy resin portion of SMD LED while it is exposed to the high temperature.

b. Care must be taken not to rub the epoxy resin portion of SMD LED with a hard or sharp edged article such as the sand blast and the metal hook as the epoxy resin is rather soft and liable to be damaged.